

DESCRIPTION

Insulated Metal Substrate (IMS), based aluminium clad with ED copper foil on the opposite side. It is designed for the reliable thermal dissipation of circuitry. A proprietarily formulated reinforced-polymer-ceramic bonding layer with a high thermal conductivity and dielectric strength allows us to guarantee thermal endurance.

The material is supplied with a film on the aluminium side to protect it against wet PCB processes.

ROHS compliance directive 2002/95/EC and REACH N° 1907/2006

STANDARD CONSTRUCTIONS

Aluminium thickness, μm (in)	1500 (0,059)	Aluminium Alloy / Treat	5052
Insulation thickness	100 (3.6mils)	Dielectric thickness tolerance	$\pm 20 \mu\text{m}$ (+/- 0.8 mils)
ED copper thickness, μm (in)	105 (3oz)		

UL Approved , QMST2 File: E47820

(1) Electrical proof test. Verification at 1150 V_{dc}

PROPERTIES (*) 1500 μm Al / 90 μm dielectric / 105 μm Cu	TEST METHOD	UNITS	TYPICAL VALUES	Values
Time to blister at 288°C, floating on solder (50 x 50 mm)	IEC-61189	Sec	>120	>60
Copper Peel strength, after heat shock 20 sec/288°C Cu105	IPC-TM 650-2.4.8	N/mm (Lb/in)	2,0 (11,5)	>1,8 (>10,3)
Dielectric breakdown voltage, AC (2) 100mic	IPC-TM 650-2.5.6.3	kV	5	4
Proof Test, DC (1)	--	V	1150	1150
Thermal conductivity (dielectric layer) (2)	ASTM-D 5470	W/mK (W/inK)	1,30 (0,032)	1,30 (0,032)
Thermal conductivity (Copper+dielectric+aluminium) (3)	ASTM-D 5470	W/mK (W/inK)	18,9	18,9
Thermal conductivity (dielectric layer) (2)	DT-5136	W/mK (W/inK)	2,0 (0.049)	2,0 (0.049)
Thermal impedance (dielectric layer)	ASTM-D 5470	Kcm ² /W (Kin ² /W)	0,77 (0,12)	0,77 (0,12)
Surface resistance after damp heat and recovery	IEC-61189	M Ω	10 ⁵	10 ⁵
Volume resistivity after damp heat and recovery	IEC-61189	M Ωm	10 ⁴	10 ⁴
Relative permittivity after damp heat and recovery, 10 kHz	IEC-61189	-	4,5	4,5
Dissipation factor after damp heat and recovery 10 kHz	IEC-61189	-	0,02	0,02
Comparative tracking index (CTI)	IEC-61112	V	600	>550
Permittivity	--	pF/m (pF/in)	6,7 (39,4)	6,7 (39,4)
Flammability, according UL-94, class	UL-94	Class	V-0	V-0
Glass transition temperature of dielectric layer (by DSC)	IPC-TM 650-2.4.25	°C	120	120
Maximum operating temperature	--	°C	130	130

(*) Values or parameters measured with a destructive method or limited size for the test sample must be considered as a representative values, and not as guaranteed values. They are not guaranteed over 100% of the material.

(2) **Dielectric Breakdown test**, test is a material destructive laboratory test. It is performed according the IPC-TM-650 part 2.5.6.3., by raising AC voltage until electric failure on a relatively small surface area of the dielectric layer using metal electrodes. Values should be taken as a material reference, and not as guaranteed values.

(3) **Thermal conductivity** of the full stack of IMS: copper 70mic + dielectric 100 micron (4 mils) + Aluminium 1,5mm (0,059")

AVAILABILITY	
STANDARD SHEET SIZES mm. (in)	1175x1065 (46'2x41'9), 1225x925 (48'2x36'4), 1215x1015 (47'8x39'9). (Also available in cut to size panels)
Tolerance	+5/-0 mm (0,2 in)
Squareness	3 mm (0,11 in) max., as differential between diagonal measurements.
Standard size tolerance in panels	+/- 0,3 mm. (0,0118 in)

The data is based on typical values of standard production and should be considered as general information. Our company reserves the right to future changes. It is the responsibility of the user to ensure that the product complies with his requirements.